

In the Specification:

Please replace the paragraph at page 1, lines 23 to 27, with a replacement paragraph amended as follows:

Thereafter, the introduced resin sets. Thus, a resin ~~mold~~ molded product is formed. Then, the mold pair is opened. The resin ~~mold~~ molded product is taken out from the one mold. Then, the resin ~~mold~~ molded product is diced and divided into a plurality of semiconductor packages. Thus, a semiconductor package as a final ~~produce~~ product is complete.

Please replace the paragraph at page 4, lines 18 to 23, with a replacement paragraph amended as follows:

The resin material of the present invention is used when electronic components mounted on a main surface of a board are resin-encapsulated by setting melted resin generated in a cavity formed in a mold pair. Further, the resin material is a solid, ~~[[row]]~~ raw material for the melted resin. Further, the resin material has such size and shape that correspond to the size and shape of the cavity.

Please replace the paragraph at page 4, lines 24 to 29, with a replacement paragraph amended as follows:

To the resin material, heat is transmitted ~~[[form]]~~
from the surfaces of the mold that form the cavity.
Therefore, when this material is used in the method of
resin encapsulation in accordance with the other aspect of
the invention described above, the heat transmitted from
the surfaces of the mold can be effectively used and the
melted resin can be obtained in a very short time period.

[RESPONSE CONTINUES ON NEXT PAGE]

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